

ieMRC and TWI Technical Seminar

Developments in Interconnection, Assembly and Packaging

TWI, Granta Park, Abington, Cambridge

Tuesday, 2nd December 2008

- 9:30 Arrivals and Coffee**
- 10:00 Introduction and Welcome to TWI, Roger Wise (TWI)
- 10:15 Interconnection, Assembly and Packaging and the ieMRC, Martin Goosey (ieMRC)
- 10:30 3D Holographic Lithography, Luke Seed (University of Sheffield)
- 11:00 Title to be confirmed, Davide de Maio (NPL)
- 11:30 Coffee**
- 11:50 Design and Analysis Tools - Current Status and Future Challenges, Chris Bailey (University of Greenwich)
- 12:20 Direct writing of metal tracks onto polyimide substrates Marc Desmulliez (Heriot-Watt University)
- 12:50 Lunch and Networking**
- 1:30 The ieMRC Opto-PCB Flagship project, Dave Milward (Xyratex) and David Selviah (University College, London)
- 2:10 Joined for life: state-of-the-art packaging processes, from chip interconnect to package sealing, Helen Goddin (TWI)
- 2:40 Afternoon tea**
- 3:00 Trends in Advanced Packaging Technologies, Andy Longford (IMAPS)
- 3:30 Precision Reliability: Lifetime Prediction with Early Warning, Damien Kirkpatrick (TWI)
- 4:00 Meeting Close and Departures**

This free event is open to all but registration is essential as numbers are limited. To confirm a place at this seminar contact Kate Cogan at k.a.j.cogan@lboro.ac.uk

